

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An electrostatic chuck having an insulation layer including a mount plane on which a wafer is mounted, an inner electrode ~~provide~~ provided in the insulation layer, and projecting portions ~~protruded~~ protruding from the mount plane which include contact planes ~~to be contacted to the~~ that contact said wafer;

 wherein a backside gas is ~~flowed~~ flows in a space defined by the said mount plane, the said projecting portions, and the wafer ~~under such a condition that the wafer is attracted to the~~ said mount plane so as to maintain a temperature uniformity of the wafer; and

 ~~comprising a construction such that~~ wherein a total amount of ~~areas~~ area of the said contact planes of the said projecting portions is ~~not less than~~ in a range of 5% and ~~not more than~~ to 10% with respect to ~~of~~ an area of the said inner electrode, and heights ~~a height of the each said projecting portions are not less than~~ portion is in a range of 5 μm and ~~not more than~~ to 10 μm .

2. (Currently Amended) The electrostatic chuck according to claim 1, wherein ~~diameters~~ a diameter of the each said projecting portions ~~are not less than~~ portion is in a range of 1.0 mm and ~~not more than~~ to 2.0 mm.

3. (Currently Amended) The electrostatic chuck according to claim 1, wherein the said projecting portions are aligned side-by-side continuously.

4. (Currently Amended) A substrate processing apparatus wherein a predetermined process is applied to a plane of a substrate, said apparatus comprising:

- a process chamber in which the predetermined process is performed;
- ~~the~~ said electrostatic chuck set forth in claim 1 ~~used for~~ that electrostatically ~~attracting~~ attracts and ~~holding~~ holds the substrate at a predetermined position in the said process chamber; and
- a power source ~~for attracting~~ ~~used for~~ that electrostatically ~~attracting~~ attracts the substrate to ~~the~~ said electrostatic chuck.